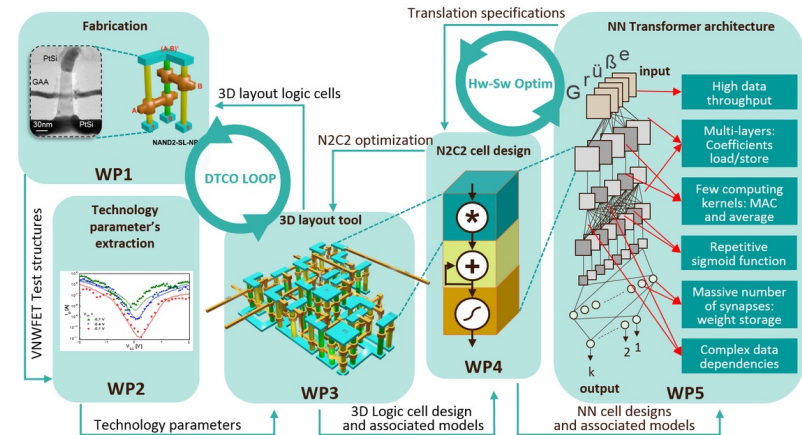
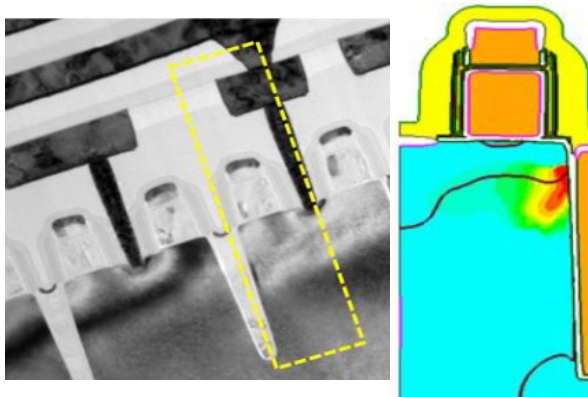


Journée Thématique

3D : du dispositif au système

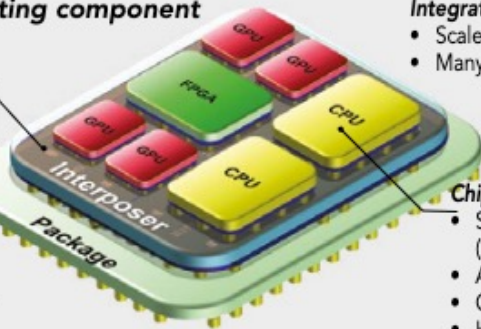
Lundi 20 novembre 2023 – INL (Lyon)



Scalable computing component

Interposer for specialization:

- System-in-Package, Silicon (Passive or active), photonic
- Heterogeneous integration enablement
- Application specific

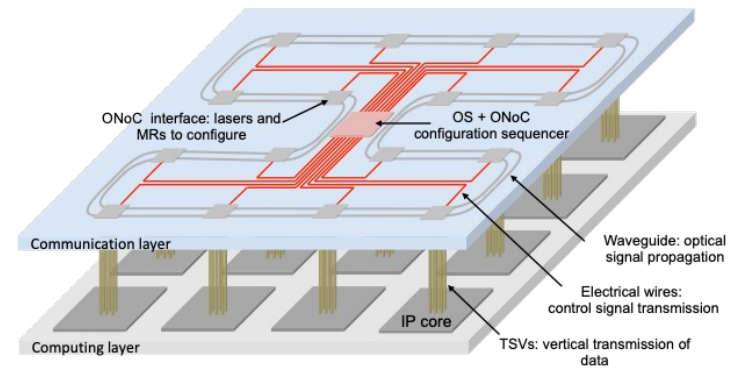


Integration for high performance:

- Scale-out
- Many-core architecture

Chiplet for low cost:

- Small to medium size chips (~1 cm² max)
- Advanced technology node
- Generic
- High volume



La journée est gratuite, inscription obligatoire sur le lien : <https://ypl.me/sJn>
 Programme : <https://amubox.univ-amu.fr/s/FgdzzYPZ4jFwSCz>

